

ECXO-2449-657.421875M TR

 [Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 2, 2017)



PLEASE NOTE: Due to the inherent proprietary nature of custom part numbers, certain parameters are intentionally excluded from this specification sheet.

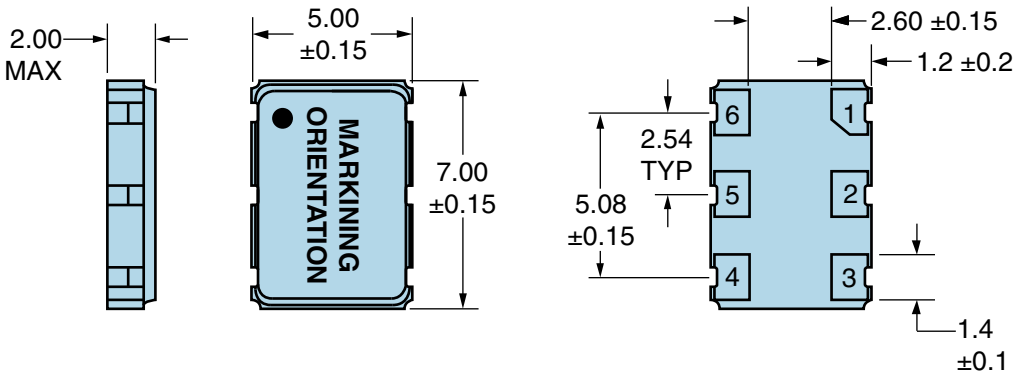
ELECTRICAL SPECIFICATIONS	
Nominal Frequency	657.421875MHz

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS	
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

ECXO-2449-657.421875M TR

[Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)

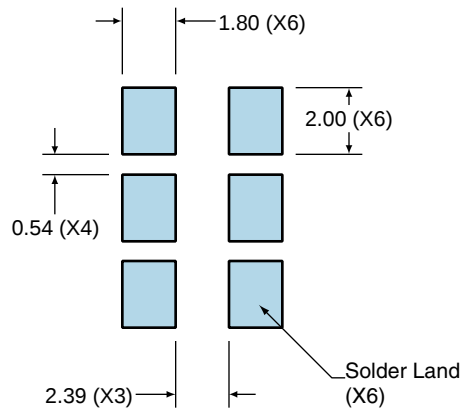


PIN	CONNECTION
1	Tri-State
2	No Connect
3	Case Ground
4	Output
5	Complementary Output
6	Supply Voltage

LINE	MARKING
1	ECXO2449
2	XXYYZZ XX=Ecliptek Manufacturing Designator Y=Last Digit Of Year ZZ=Week of Year

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

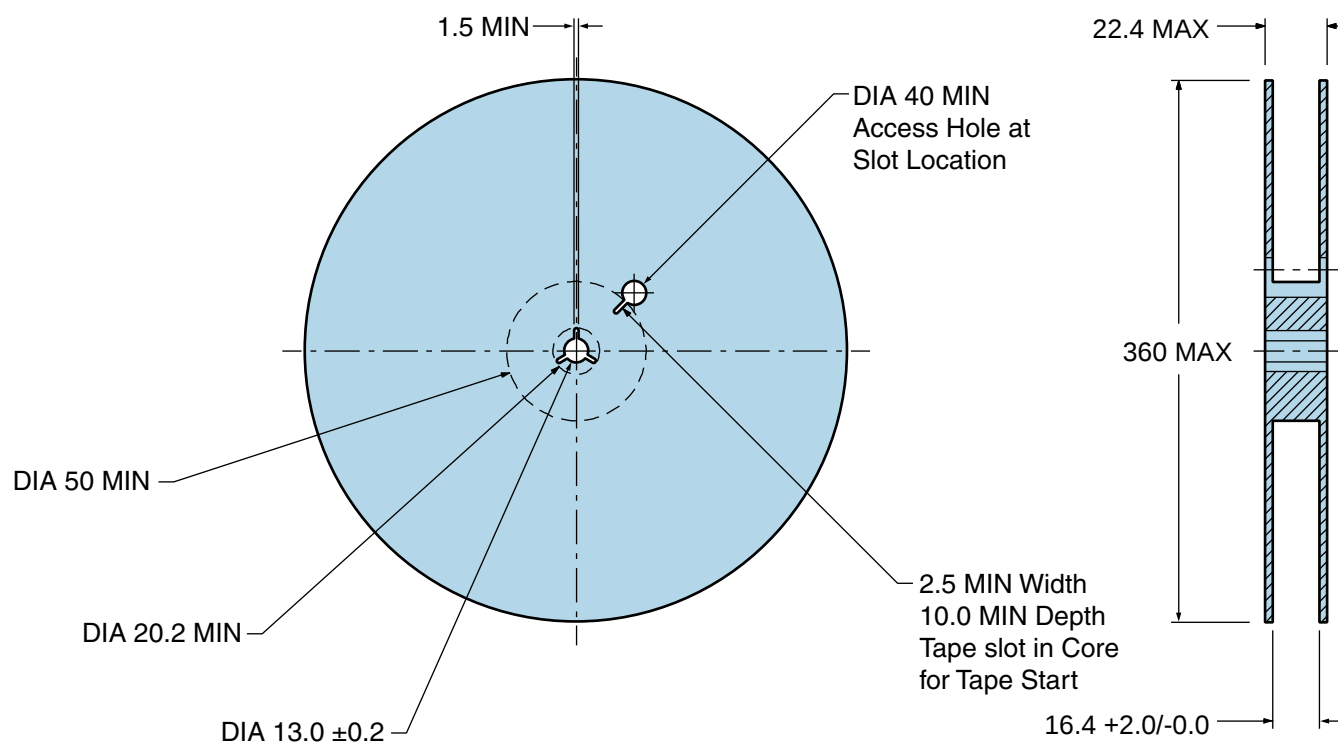
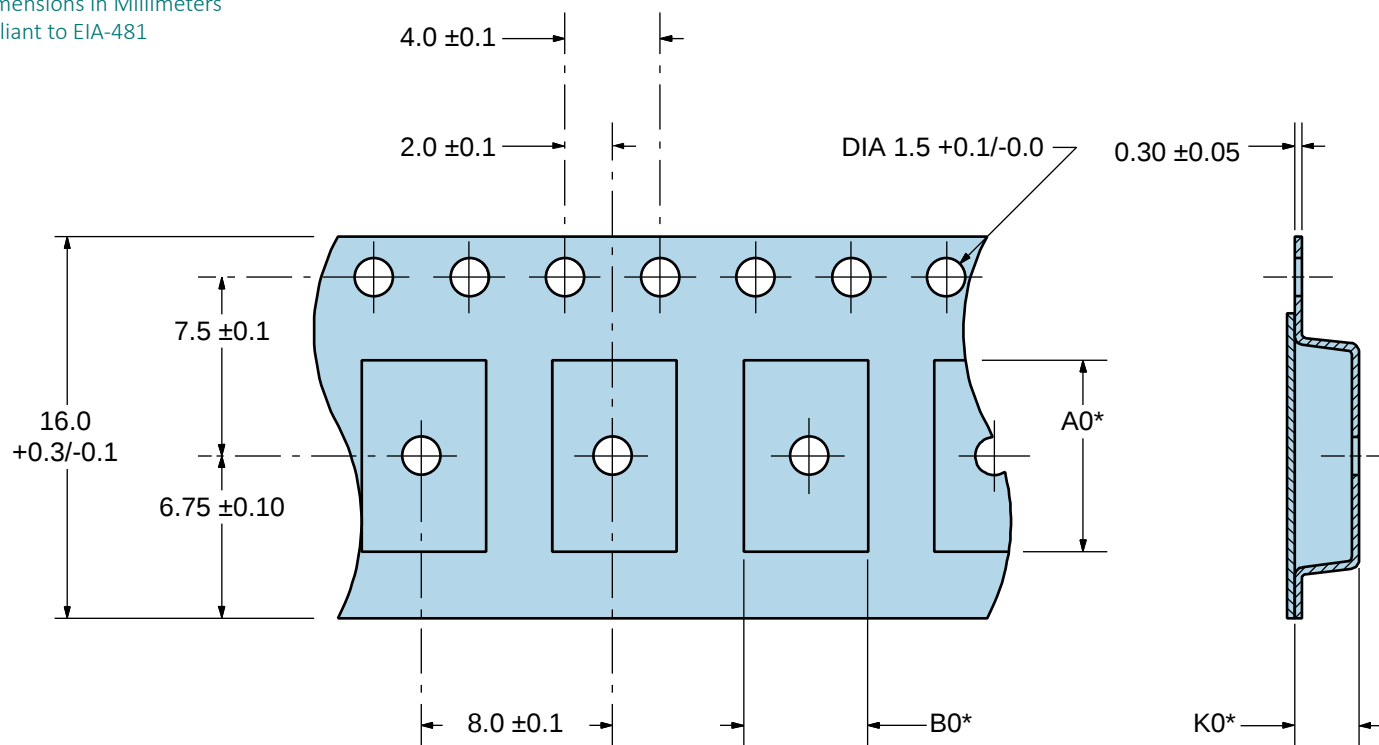
ECXO-2449-657.421875M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



ECXO-2449-657.421875M TR

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

Ts MAX to TL (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
Ramp-up Rate (TL to TP)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds
Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (TP Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1

ECXO-2449-657.421875M TR

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	240°C Maximum
Target Peak Temperature (TP Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tP)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.